

Page 13, between lines 20 and 21 insert a new paragraph as follows:

B3
Figs. 1-5 are process charts showing a producing process of the thin film-structure of this example.

Page 15, between line 20 and page 16, line 2 insert a new paragraph as follows:

B4
Moreover, instead of the paddle 12 as shown in Fig. 1, a solder bump 30 as shown in Fig. 9 or a thick portion 31 as shown in Fig. 10, made of the same material as or the different one from the thin film may be formed on the tip of the thin film. Thereby, the thin film-structure can have a one side-fixed beam-like shape with such a thin film bending downward.

In this example and the examples shown in Figs. 9 and 10, the weight of the tip of the thin film constituting the one side-fixed beam-like thin film-structure was increased to relatively enhance its deflection degree. However, if the deflection degree is not increased such a means is not needed. Moreover, although the thin film 14 was not bent toward the etch pit 16 in this example, it may be bent backward by turning the substrate over.

IN THE CLAIMS:

Please replace claims 3, 11, 18 and 22 as follows:

B5
3. (Amended) A method for producing a thin film-structure comprising the steps of:
forming on a substrate a thin film made of an amorphous material having a supercooled liquid phase region,
heating the thin film to a temperature within the supercooled liquid phase region and thereby deforming the thin film to a given shape, and
cooling the thin film to room temperature from the temperature within the supercooled liquid phase region to stop deforming the thin film and thereby forming the thin film-structure.